

**AMENDMENTS TO THE SPECIFICATION**

Please amend the paragraph beginning at page 16, line 23, as follows:

In addition, it can be seen from FIG. 10 how the contact areas 24 may serve as control marks when the integrated circuit is applied. The side edges of an integrated circuit to be applied later are identified by the reference numeral 51. If the integrated circuit is optimally applied to the substrate, part of the contact areas 24 always projects beyond the side edges 51, in the way represented in FIG. 10. Ideally, the side edges 51 of the integrated circuit and the edges of the contact areas are aligned parallel to one another. It is consequently possible to carry out a visual check to ascertain whether the flip-chip bonding of the integrated circuit with the contact areas of the insertion-side metallization has correctly taken place. In the region that the integrated circuit is to be applied, the insertion-side metallization includes, in one embodiment, spacers 60 which ensure plane-parallelism between the integrated circuit and the insertion side of the substrate. These spacers 60, which may likewise be part of the insertion-side metallization, but do not have to be, contribute to stopping the integrated circuit from bowing when the carrier element is applied.